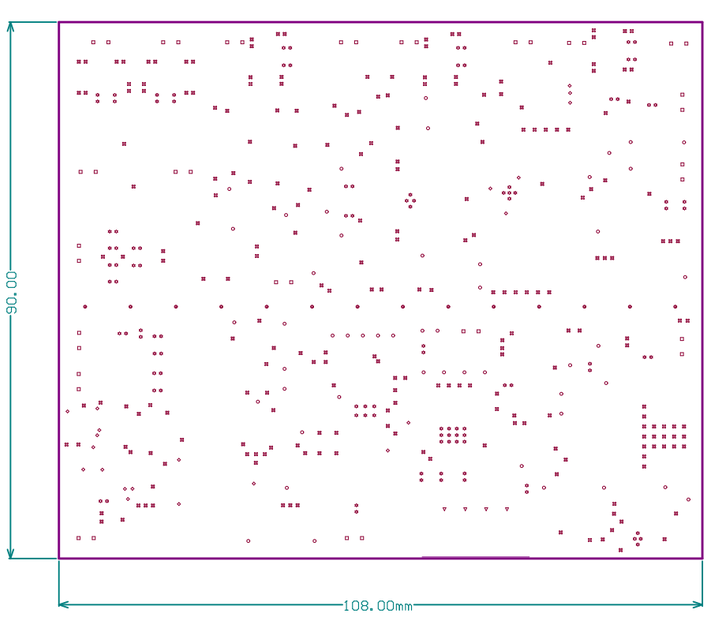
Layer	Name	Material	Thickness	Constant	Board Layer Stack	Board Layer Stack
1	Top Overlay					
2	Top Solder	Solder Resist	0.40mil	3.5		
3	Top Layer	Copper	1.40mil			
4	Dielectric1	FR-4 High Tg	59.20mil	4.8		
5	Bottom Layer	Copper	1.40mil			
6	Bottom Solder	Solder Resist	0.40mil	3.5		
7	Bottom Overlay					

Symbol	Count	Hole Size	Plated	Hole Type	Hole Length
✡	107	7.87mil (0.200mm)	PTH	Round	-
◇	21	12.00mil (0.305mm)	PTH	Round	-
⊠	235	16.00mil (0.406mm)	PTH	Round	-
◎	14	32.00mil (0.813mm)	NPTH	Slot	200.00mil (5.080mm)
○	50	40.00mil (1.016mm)	PTH	Round	-
□	40	43.31mil (1.100mm)	PTH	Round	-
▽	4	47.24mil (1.200mm)	PTH	Round	-
	471 Total				

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



Drill Table
FOR 7.874MIL DRILL +0/-7.874MIL
FOR 12MIL DRILL +0/-12MIL
FOR 16MIL DRILL +0/-16MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL

1000.00mil

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
108MM X 90MM

Number of Layers : 2
MIN. TRACK WIDTH: 10 MIL
MIN. CLEARANCE: 7.7 MIL
MIN. VIA DRILL SIZE: 7.874 MIL
MINIMUM ANNULAR RING 6 MIL (0.1524 mm) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [X] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS --> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [ ] NO [X]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [ ] NO [X]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

PROJECT TITLE: TIDA-010008_IO-Power+Protection
DESIGNED FOR: Public Release
FILE NAME: TIDA-010008_IO-Power+Protection.PcbDoc

ENGINEER: Sreenivasa	LAYOUT BY: Avinash N
SCALE: 1.00	ALTIUM DESIGNER VERSION: 18.1.9.240

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-010008_IO-Power+Protection	SVN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 010008	
PLOT NAME = Fabrication Drawing	GENERATED : 4/29/2019 2:24:06 PM	TEXAS INSTRUMENTS

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